



SOT23-6 MOSFET Material Safety Data Sheet

Material Content Declaration					
Material name	Substance name e.g. Copper (Cu), Gold (Au)	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
Lead Frame 34.69%	Copper (Cu)	7440-50-8	10.531	99.91	346,642.5
	Phosphorus (P)	7723-14-0	0.003	0.03	98.7
	Iron (Fe)	7439-89-6	0.006	0.06	197.5
	Total		10.54		
Bonding Wire 0.05%	Copper (Cu)	7440-50-8	0.015	100	493.7
	Total		0.015		
Wafer 1.43%	Silicon (Si)	7440-21-3	0.43350	99.6565	14,269.3
	Silver (Ag)	7440-22-4	0.00125	0.287	41.1
	Aluminum(Al)	7429-90-5	0.00011	0.0251	3.6
	Nickel (Ni)	7440-02-0	0.00008	0.0179	2.6
	Copper (Cu)	7440-50-8	0.00004	0.0102	1.3
	Titanium (Ti)	7440-32-6	0.00001	0.0017	0.3
	Tin (Sn)	7440-31-5	0.00001	0.0016	0.3
	Total		0.435		
Molding 58.16%	Silica (SiO ₂)	60676-86-0	13.095	74.11	431,040.2
	Aluminum hydroxide	21645-51-2	1.202	6.8	39,565.5
	Epoxy resin	29690-82-2	2.209	12.5	72,712.3
	Phenolic resin	9003-36-5	1.096	6.2	36,076.4
	carbon black	1333-86-4	0.068	0.39	2,238.3
	Total		17.67		
Ag paste 5.37%	Silver (Ag)	7440-38-2	1.312	80.5	43,186.3
	epoxy resin	9003-36-5	0.196	12	6,451.6
	butane	2425-79-8	0.098	6.0	3,225.8
	dapsone	80-08-0	0.024	1.5	790.0
	Total		1.63		
Plating 0.3%	Tin (Sn)	7440-31-5	0.09	100	2,962.5
	Total		0.09		
	Total mass (mg)		30.38		